P54/74FCT139/A/C (P54/74PCT139/A/C)
HIGH-SPEED DUAL 1-OF-4 DECODER

FEATURES

- **Function, Pinout, and Drive Compatible with the FCT and F Logic**
- **FCT-C speed at 4.8ns max. (Com'l)**
  FCT-A speed at 5.9ns max. (Com'l)
- **CMOS V_{OH} Levels for Low Power Consumption — Typically 1/3 of FAST Bipolar Logic**
- **Edge-rate Control Circuitry for Significantly Improved Noise Characteristics**
- **ESD protection exceeds 2000V**
- **Inputs and Outputs Interface Directly with TTL, NMOS, and CMOS Devices**
- **Outputs Meet Levels Required for CMOS Static RAM Low Power Standby Mode**
- **64 mA Sink Current (Com'l), 48 mA (Mil)**
  15 mA Source Current (Com'l), 12 mA (Mil)
- **Dual 1-of-4 Decoder with Enable**
- **Manufactured in 0.8 micron PACE Technology™**

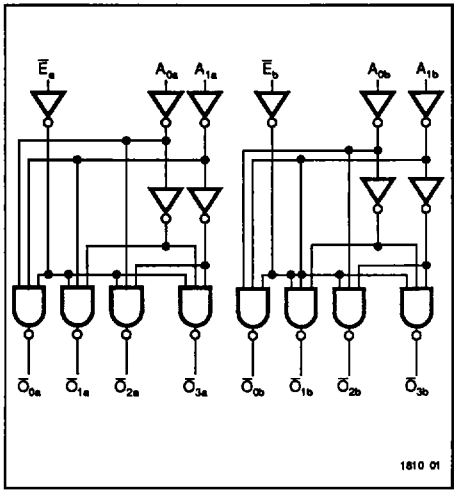
DESCRIPTION

The 'FCT139 are dual 1-of-4 decoder which has two independent decoders, each of which accept two binary weighted inputs (A_0–A_1) and provide four mutual exclusive active LOW outputs ($\overline{O}_0$–$\overline{O}_3$). Each decoder has an active LOW enable ($\overline{E}$). When $\overline{E}$ is HIGH, all outputs are forced HIGH.

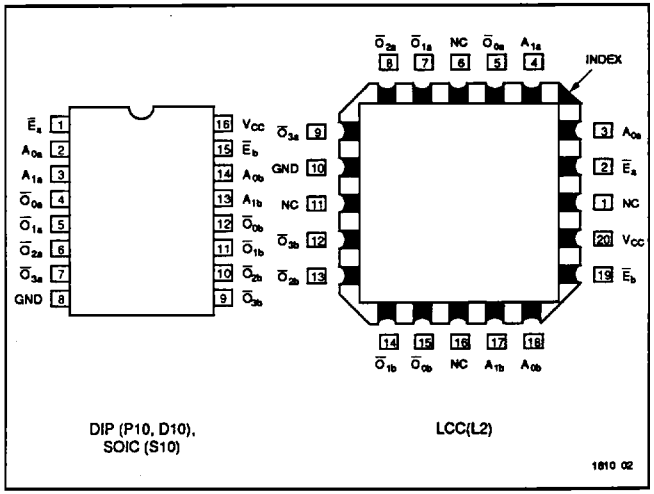
The 'FCT139 is manufactured using PACE Technology™ which is Performance Advanced CMOS Engineered to use 0.8 micron effective channel lengths giving 500 picoseconds loaded* internal gate delays. PACE Technology includes two-level metal and epitaxial substrates. In addition to very high performance and very high density, the technology features latch-up protection, single event upset protection, and is supported by a Class 1 environment volume production facility.

*For a fan-in/fan-out of 4, at 85°C junction temperature and 5.0V.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATIONS



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ABSOLUTE MAXIMUM RATINGS[1,2]

Symbol	Parameter	Value	Unit
T_{STG}	Storage Temperature	–65 to +150	°C
T_A	Ambient Temperature Under Bias	–65 to +135	°C
V_{CC}	V_{CC} Potential to Ground	–0.5 to +7.0	V
I_{IN}	Input Current	–30 to +5.0	mA
I_{OUTPUT}	Current Applied to Output	120	mA
V_{IN}	Input Voltage	–0.5 to V_{CC} + 0.5	V
V_{OUT}	Voltage Applied to Output	–0.5 to V_{CC} + 0.5	V

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Notes:

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.
2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	–55°C	+125°C
Commercial	0°C	+70°C

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Supply Voltage (V_{CC})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

1810 Tbl 04

DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter		Min	Typ[1]	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		
V_{IL}	Input LOW Voltage				0.8	V		
V_H	Hysteresis			0.35		V		All inputs
V_{CD}	Input Clamp Diode Voltage			–0.7	–1.2	V	MIN	I_{IN} = –18mA
V_{OH}	Output HIGH Voltage	V_{CC} = 3V, V_{IN} = 0.2V, or V_{CC} – 0.2V	V_{CC} – 0.2	V_{CC}		V		I_{OH} = –32µA
		Military/Commercial (CMOS)	V_{CC} – 0.2	V_{CC}		V	MIN	I_{OH} = –300µA
		Military (TTL)	2.4	4.3		V	MIN	I_{OH} = –12mA
		Commercial (TTL)	2.4	4.3		V	MIN	I_{OH} = –15mA
V_{OL}	Output LOW Voltage	V_{CC} = 3V, V_{IN} = 0.2V, or V_{CC} – 0.2V		GND	0.2	V		I_{OL} = 300µA
		Military/Commercial (CMOS)[3]		GND	0.2	V	MIN	I_{OL} = 300µA
		Military (TTL)		0.3	0.5	V	MIN	I_{OL} = 32mA
		Commercial (TTL)		0.3	0.5	V	MIN	I_{OL} = 48mA
		Commercial (TTL)		0.3	0.5	V	MIN	I_{OL} = 64mA
I_{IH}	Input HIGH Current				5	µA	MAX	V_{IN} = V_{CC}
I_{IL}	Input LOW Current				–5	µA	MAX	V_{IN} = GND
I_{IH}	Input HIGH Current[3]				5	µA	MAX	V_{OUT} = 2.7V
I_{IL}	Input LOW Current[3]				–5	µA	MAX	V_{OUT} = 0.5V
I_{OS}	Output Short Circuit Current[2]		–60	–120		mA	MAX	V_{OUT} = 0.0V
C_{IN}	Input Capacitance[3]			5	10	pF		All inputs
C_{OUT}	Output Capacitance[3]			9	12	pF		All outputs

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Notes:

1. Typical limits are at V_{CC} = 5.0V, T_A = +25°C ambient.
2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{os} tests should be performed last.
3. This parameter is guaranteed but not tested.

DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ[1]	Max	Units	Conditions
I_{CC}	Quiescent Power Supply Current (CMOS inputs)	0.003	0.5	mA	V_{CC} = MAX, f_1 = 0, Outputs Open, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	0.5	2.0	mA	V_{CC} = MAX, V_{IN} = 3.4V[2], f_1 = 0, Outputs Open
I_{CCD}	Dynamic Power Supply Current[3]	0.15	0.3	mA/ mHz	V_{CC} = MAX, One Input Toggling, 50% Duty Cycle, Outputs Open, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
I_C	Total Power Supply Current[5]	1.7	4.5	mA	V_{CC} = MAX, f_1= 10 MHz, 50% Duty Cycle, Outputs Open, One Input Toggling, and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		2.0	5.5	mA	V_{CC} = MAX, f_1= 10 MHz, 50% Duty Cycle, Outputs Open, One Input Toggling, and V_{IN} = 3.4V or V_{IN} = GND
		3.2	7.5	mA	V_{CC} = MAX, f_1= 10 MHz, 50% Duty Cycle, Outputs Open, One Input Toggling on Each Decoder, and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		3.7	9.5	mA	V_{CC} = MAX, f_1= 10 MHz, 50% Duty Cycle, Outputs Open, One Input Toggling on Each Decoder, and V_{IN} = 3.4V or V_{IN} = GND

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Notes:

1. Typical values are at V_{CC} = 5.0V, +25°C ambient and maximum loading.
2. Per TTL driven input (V_{IN} = 3.4V); all other inputs at V_{CC} or GND.
3. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
4. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
5. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
   $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD}(f_0/2 + f_1 N_1)$
   I_{CC} = Quiescent Current with CMOS input levels
   ΔI_{CC} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)
   D_H = Duty Cycle for TTL Inputs High
   N_T = Number of TTL Inputs at D_H
   I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
   f_0 = Clock Frequency for Register Devices (Zero for Non-Register Devices)
   f_1 = Input Frequency
   N_1 = Number of Inputs at f_1
   All currents are in milliamps and all frequencies are in megahertz.

TRUTH TABLE

Inputs			Outputs			
$\overline{E}$	A_0	A_1	$\overline{O}_0$	$\overline{O}_1$	$\overline{O}_2$	$\overline{O}_3$
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	H	L	H	L	H	H
L	L	H	H	H	L	H
L	H	H	H	H	H	L

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H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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AC CHARACTERISTICS

Sym	Parameter	'FCT139				'FCT139A				'FCT139C				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min.[1]	Max.	Min.[1]	Max.	Min.[1]	Max.	Min.[1]	Max.	Min.[1]	Max.	Min.[1]	Max.		
t_{PLH} t_{PHL}	Prop Delay A_0 or A_1 to $\overline{O}_n$	1.5	12.0	1.5	9.0	1.5	7.8	1.5	5.9	1.5	6.6	1.5	4.8	ns	1, 5
t_{PLH} t_{PHL}	Prop Delay $\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	1.5	9.0	1.5	8.0	1.5	7.2	1.5	5.5	1.5	6.2	1.5	5.0	ns	1, 5

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Note:

1. Minimum limits are guaranteed but not tested on Propagation Delays.

DEFINITION OF FUNCTIONAL TERMS

Pin Names	Description
A_0, A_1	Address Inputs
$\overline{E}_a$, $\overline{E}_b$	Enable Inputs (Active LOW)
$\overline{O}_0$–$\overline{O}_3$	Outputs (Active LOW)

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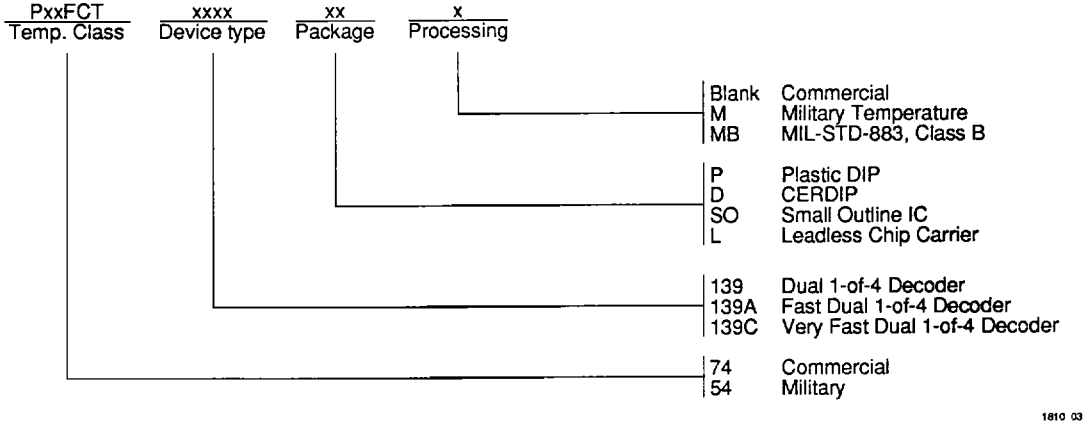
ORDERING INFORMATION



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